

## ELECTRONICS MANUFACTURING OVERVIEW

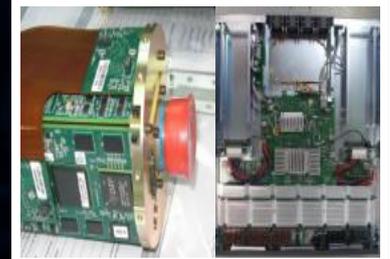
### Unit Location: Mysore

#### Infrastructure:

- Production areas – Unit 1: 168,000 sq. ft.; Unit 2: 217,800 sq. ft.
- Surface-mount technology lines and plated through-hole lines
- Product integration lines
- Electrical and functional testing
- Electrostatic discharge and moisture-sensitive device compliance

#### Capabilities:

- Design-for-Excellence services
- Complex printed circuit board assembly
- Vapor phase reflow soldering
- Selective soldering
- High-mix, low- to medium-volume production
- Conformal coating and bonding
- Potting and encapsulation
- Press-fit connector installation
- Gold removal (de-golding)
- Mixed metallurgy for ball grid arrays (BGAs)
- BGA underfill
- PCB cleaning with the Aquastorm inline cleaning system
- Advanced testing
- Radio frequency and microwave capabilities
- Cable and wire harnesses
- System integration
- Computerized life-cycle data management
- RoHS-compliant manufacturing



#### Certifications:

ISO 9001 | ISO 14001 | OHSAS 18001 | AS 9100 | NADCAP-AC7120 |  
NADCAP-AC7121 | ISO 13485 | ISO/TS 22163 | ISO/IEC 27001

#### NADCAP-Approved Facility

**1,000+**

Employees

**30%**

10+ years  
experience

**42%**

Systems  
integration

**Client Award**

Honeywell, GE,  
Bosch

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